深圳市雅晶鑫电子有限公司

Shenzhen Yajingxin Electron Co.,Ltd

产品规格书

SPECIFICATION FOR PRODUCT

品　　名
PARTNAME　　OSC SMD 2016

规　　格
SPECIFICATION　25.000MHz / 1.62～3.63V

客　　户
CUSTOMER

客户 料号
CUSTOMER P/N

雅晶鑫 料号
TONGJING P/N　G201625MUBCE20

日　　期
DATE　　2024 年 08 月 19 日

编　　号
NUMBER　　T240830002

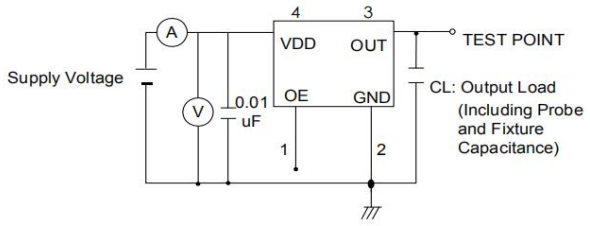
拟制：陈昭昭　　复核：鄭利　　批准：李虹

深圳市雅晶鑫电子有限公司

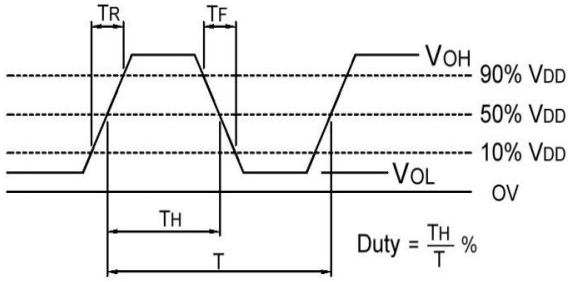
Shenzhen Yajingxin Electron Co.,Ltd

DESCRIPTION			CONTENTS
1	Holder Type	封装盒型	SMD 2016
2	Nominal Frequency	标称频率	25.000MHz
3	Frequency Tolerance @25℃±2℃	频率公差	±10ppm
4	Operable Temperature Range	工作温度	-40℃～ +85℃
5	Output Load	输出负载	15 pF
6	Supply Voltage	工作电压	1.62～3.63Vdc
7	Output Waveform	输出波形	CMOS
8	Current Comsuption	电流消耗	Operating 10mA
			Standby 10uA
9	Duty Cycle	占空比	50±10%
10	Output Rise/Fall Time	输出上升/下降时间	5ns
11	Output Level	输出电平	Output High(Logic “1”) 0.9Vdd MIN
			Output Low(Logic “0”) 0.1Vdd MAX
12	Enable Delay Time	使能延迟	150 uS MAX
13	Storage Temperature	储存温度	-55℃～ +125℃
14	Aging Rate	年老化率	±3ppm/Year
15	Start-up Time	启动时间	5ms

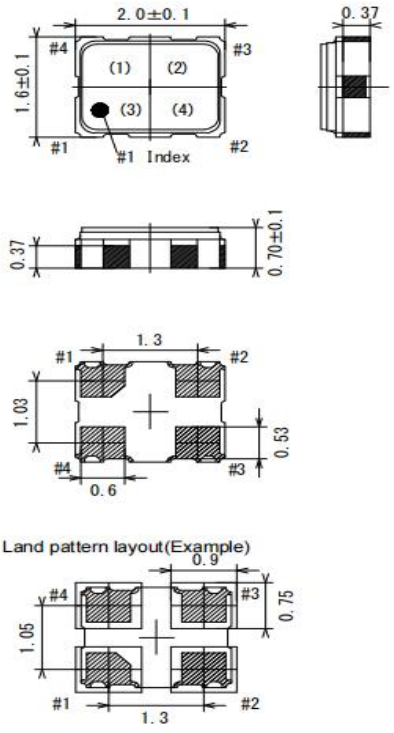
- **Test Circuit (CMOS Load)**



- **Output Waveform (CMOS Load)**



- **Outline Dimensions(unit: mm)**



unit: mm
Dimensional Tolerance: ±0.1
(Unless otherwise noted)

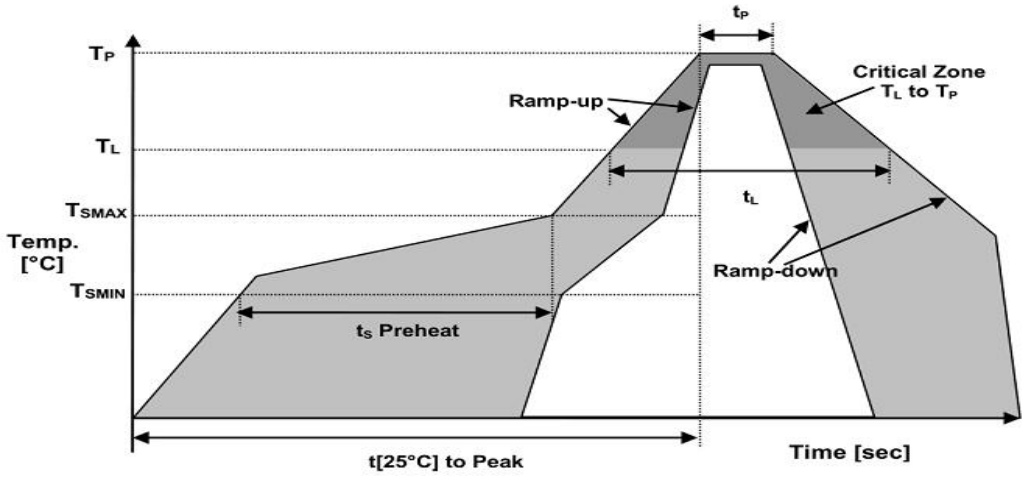
Pin Connection

Name	Connection
1	E/D
2	GND
3	Fout
4	Vdd

Functio

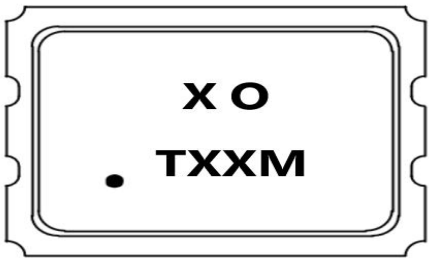
Pin1 Input	Pin3 Output
High level	Oscillation
Low level	Oscillation stop

● Reflow sodering



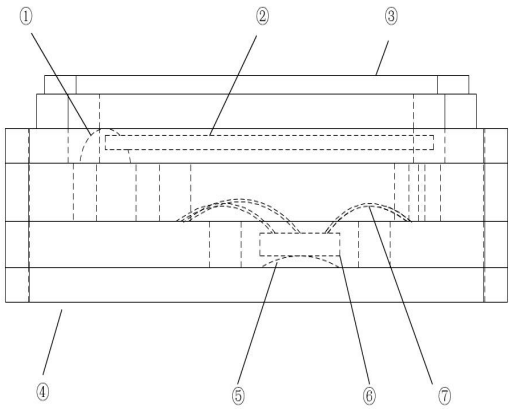
Reflow Profile		
Temperature MIN Preheat	T_{SMIN}	150℃
Temperature MAX Preheat	T_{SMAX}	200℃
Time（T_{SMIN} -T_{SMAX}）	t_S	60-180sec
Temperature	T_L	217℃
Peak Temperature	T_P	260℃
Ramp-up Rate	R_{UP}	3℃/sec max
Ramp-Down Rate	R_{DOWN}	6℃/sec max
Time within 5℃ of Peak Temperature	t_P	10sec
Time t(25℃) to Peak Temperature	t(25℃)to Peak	480sec
Time	t_L	60-150sec

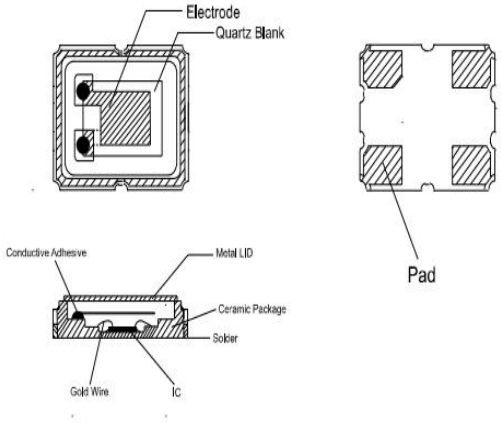
● Marking



XO:　Oscillator Code
T:　TJ Logo
XX:　Frequency Code
M:　Frequency Units
●:　Pin1 Index

- **Structure Illustration**

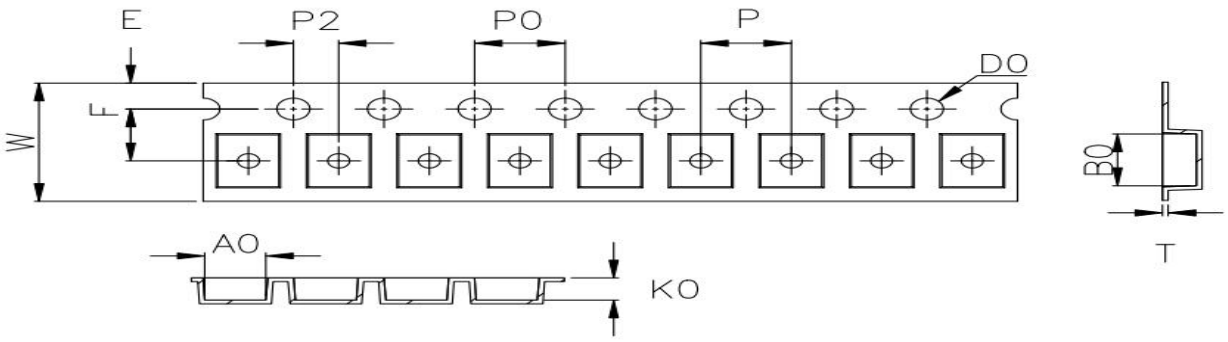




NO.	Components	Materials
1	Conductive Adhesive	Ag+Silicone resin
2	Crystal Blank	SiO2
3	Lid	Fe-Ni-Co Alloy
4	Base	Ceramic+Noble Metal
5	Conductive Adhesive of Solid IC	Ag+Silicone resin
6	IC	Si
7	Gold wire	Au

- **Package**

Tape Dimensions(unit :mm)



W	8.00±0.30	P	4.00±0.05	A0	1.90±0.05
E	1.75±0.05	P0	4.00±0.05	K0	0.65±0.05
F	3.50±0.05	P2	2.00±0.05	B0	2.30±0.05
T	0.25±0.03	D0	1.55+0.10/-0